

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Yoshiyuki MOTOMIYA	04/25/2013
Koji TAKETOMI	04/01/2013
Kenichiro NOGI	04/15/2013
Takumi TAKAHASHI	04/12/2013
Katsuyuki KAYAHARA	04/09/2013
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIYO YUDEN CO., LTD.
<b>Street Address:</b>	16-20, Ueno 6-chome
<b>City:</b>	Taito-ku, Tokyo
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	110-0005
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13824897
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	9494578297
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	949-457-8296
<b>Email:</b>	KAPAT@KAPATLAW.COM
<b>Correspondent Name:</b>	Law Office of Katsuhiro Arai
<b>Address Line 1:</b>	22471 Aspan Street
<b>Address Line 2:</b>	Suite 205 C
<b>Address Line 4:</b>	Lake Forest, CALIFORNIA 92630
<b>ATTORNEY DOCKET NUMBER:</b>	TAYUX.100058AP
<b>NAME OF SUBMITTER:</b>	Katsuhiro Arai

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**PATENT**  
 REEL: 030348 FRAME: 0894

Signature:	/katsuhiro arai/
Date:	05/03/2013
Total Attachments: 2 source=Assignment_TAYUX100058ap#page1.tif source=Assignment_TAYUX100058ap#page2.tif	

**ASSIGNMENT**

WHEREAS, the undersigned inventor(s) have/has invented certain new and useful improvements in

COMMON MODE NOISE FILTER

for which the undersigned inventor(s)

will file an application for Letters Patent in the United States identified as Attorney Docket Number shown in the top margin (hereinafter "Application");

have/has filed an application, International Application No. \_\_\_\_\_, filed \_\_\_\_\_, under the Patent Cooperation Treaty, which will enter the U.S. National Phase under 35 U.S.C. §371 (hereinafter "Application");

have/has filed an application for Letters Patent in the United States, Application No. **13/824,897**, filed **March 18, 2013** (hereinafter "Application");

AND WHEREAS, TAIYO YUDEN CO., LTD, a Japanese corporation, with its principal place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo, 110-0005, Japan (hereinafter "ASSIGNEE"), desires to acquire the entire right, title, and interest in and to said improvements and said Application;

NOW, THEREFORE, in return for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor(s) do/does hereby acknowledge that the undersigned inventor(s) have/has sold, assigned, transferred and set over, and by these presents do/does hereby sell, assign, transfer and set over, unto said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under said improvements, and said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and the undersigned inventor(s) hereby authorize(s) and request(s) the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND THE UNDERSIGNED INVENTOR(S) DO/DOES HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance;

AND THE UNDERSIGNED INVENTOR(S) HEREBY covenant(s) and agree(s) that the undersigned inventor(s) will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to the undersigned inventor(s) respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, the undersigned inventor(s) execute(s) this assignment:

<b>NAME OF SOLE OR FIRST INVENTOR</b>	
first and middle [if any]	FAMILY NAME
Yoshiyuki	MOTOMIYA
Inventor's Signature	Date
<i>Yoshiyuki Motomiya</i>	4/25/2013
<b>NAME OF SECOND INVENTOR</b>	
first and middle [if any]	FAMILY NAME
Koji	TAKETOMI
Inventor's Signature	Date
<i>Koji Taketomi</i>	4/1/2013
<b>NAME OF THIRD INVENTOR</b>	
first and middle [if any]	FAMILY NAME
Kenichiro	NOGI
Inventor's Signature	Date
<i>Kenichiro Nogi</i>	4/15/2013
<b>NAME OF FOURTH INVENTOR</b>	
first and middle [if any]	FAMILY NAME
Takumi	TAKAHASHI
Inventor's Signature	Date
<i>TAKUMI TAKAHASHI</i>	4/12/2013
<b>NAME OF FIFTH INVENTOR</b>	
first and middle [if any]	FAMILY NAME
Katsuyuki	KAYAHARA
Inventor's Signature	Date
<i>Katsuyuki Kayahara</i>	Apr. 9, 2013